



PATENT

Case Docket No. MICRON.076DV1

Date: October 21, 2002

Page 1

In re application of : Weimin Li  
App. No. : 10/033,656  
Filed : December 27, 2001  
For : LOW DIELECTRIC  
CONSTANT MATERIAL FOR  
INTEGRATED CIRCUIT  
FABRICATION  
Examiner : Jamie Lynn Brophy  
Art Unit : 2822

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2327, Arlington, VA 22202, on

Oct. 21, 2002

(Date)  
Adeel S. Akhtar

Adeel S. Akhtar, Reg. No. 41,394

UNITED STATES PATENT AND TRADEMARK OFFICE  
P.O. Box 2327  
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	10	—	20	= 0 ×	\$18	= \$0
Independent Claims	2	—	3	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add					\$280	= \$0
Time Extension Fee						\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

- (X) Enclosed, please find one (1) amended drawing, with the amendments marked in red.
- (X) Return prepaid postcard.
- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

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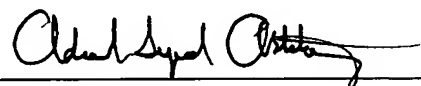
Case Docket No. MICRON.076DV1

Date: October 18, 2002

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N.076DV1

PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Weimin Li ) Group Art Unit: 2822  
Appl. No. : 10/033,656 )  
Filed : December 27, 2001 )  
For : LOW DIELECTRIC CONSTANT )  
MATERIAL FOR INTEGRATED )  
CIRCUIT FABRICATION )  
Examiner : Jamie Lynn Brophy )

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(Date)

*Adeel S. Akhtar*  
Adeel S. Akhtar, Reg. No. 41,394

AMENDMENT AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office  
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Dear Sir:

In response to the Office Action mailed May 8, 2002 (the "Office Action"), Applicant respectfully requests entry of the following amendments and reconsideration of the rejections in view of the remarks below.

IN THE CLAIMS:

Please amend the claims as set forth below.

1. (Amended) A unitary layer of insulating material directly contacting and formed between conductive elements in an integrated circuit, comprising a polysiloxane network consisting essentially of silicon, oxygen, carbon and hydrogen and incorporating carbon-silicon bonding and having a dielectric constant of less than about 3.3.

5. (Amended) An integrated circuit, comprising:  
a first conductive element providing a first electrical path of the circuit;  
a second conductive element providing a second electrical path of the circuit; and  
a unitary insulating layer directly contacting and sandwiched between the first and second conductive elements, the insulating layer comprising polysiloxane, consisting